



ECE695: Reliability Physics of Nano-Transistors Lecture 27: Correlated TDDB in Off-State HCI

Muhammad Ashraful Alam alam@purdue.edu

Copyright 2013

This material is copyrighted by M. Alam under the following Creative Commons license:



Attribution-NonCommercial-ShareAlike 2.5 Generic (CC BY-NC-SA 2.5)

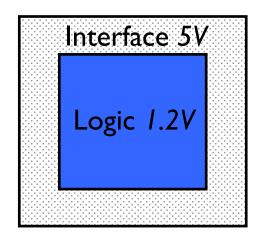
Conditions for using these materials is described at

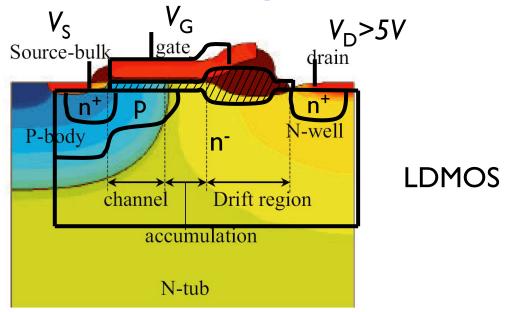
http://creativecommons.org/licenses/by-nc-sa/2.5/

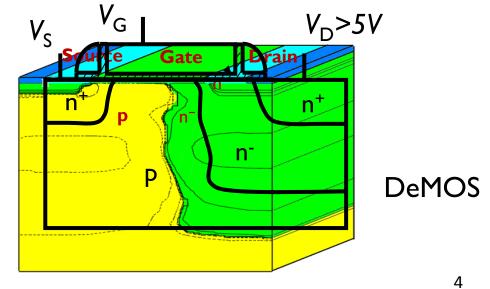
Outline

- I. Recall: ON vs. OFF State HCI Degradation
- 2. SiH vs. SiO bonds and theory of universal scaling
- 3. Dielectric Breakdown during HCI
- 4. Conclusions

Recall: HCI degradation in non-logic transistors

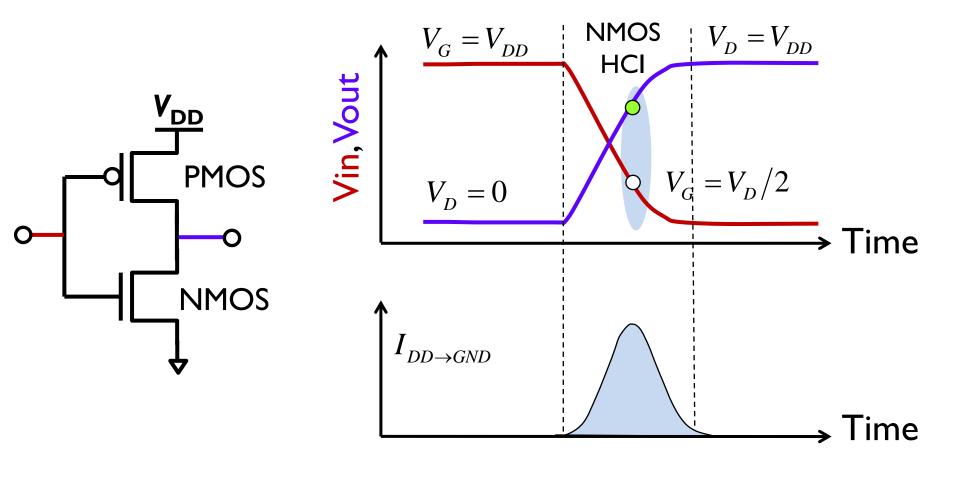






Alam ECE-695

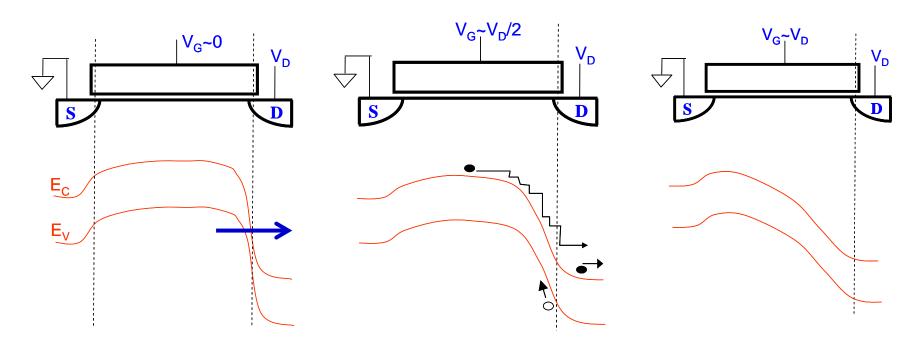
Classical HCI ... only ON state?!



True only for logic transistor, at relatively low operating voltage

Alam ECE-695 5

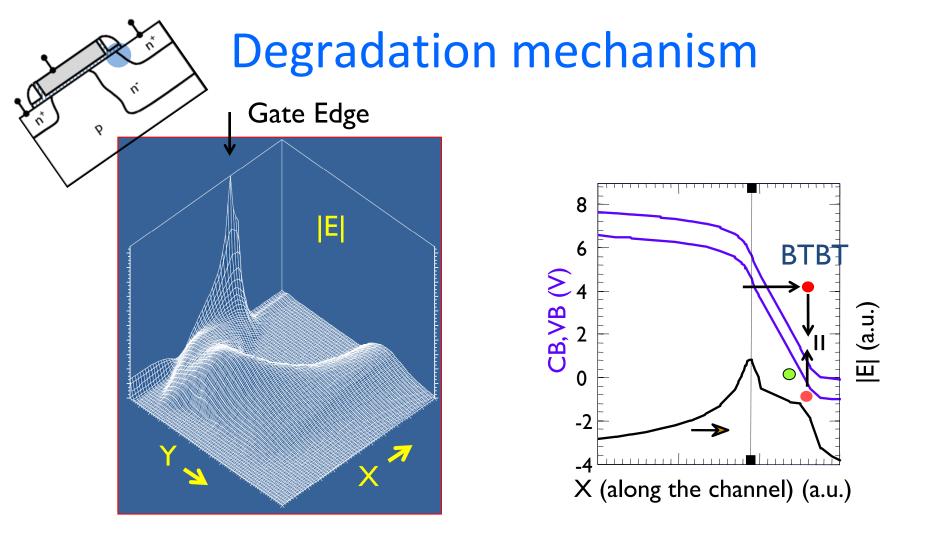
Recall: OFF state HCI is possible, if ...



... large band-to-band tunneling at high VD

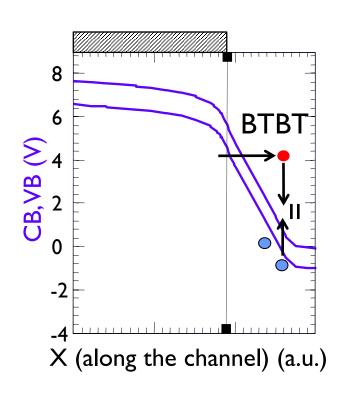
OR as parasitic degradation in accelerated tests of logic transistors

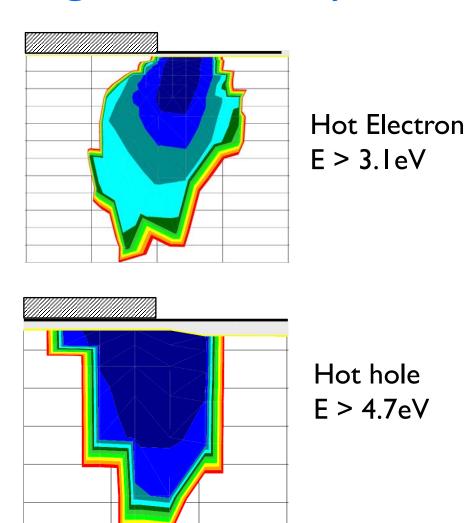
Alam ECE-695



Electric field peaks at the surface leading to BTBT & Impact ionization

Heating of electrons generated by BTBT





Impact Ionization of BTBT current generate hot carriers

Outline

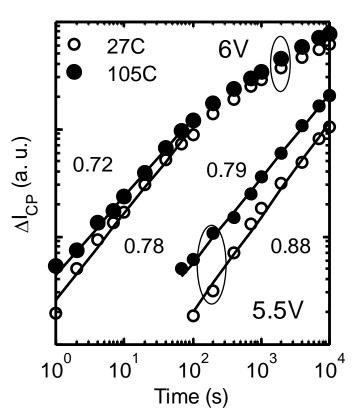
I. ON vs. OFF State HCI Degradation

2. SiH vs. SiO bonds and theory of universal scaling

3. HCI by TDDB: Puzzle of the Weibull slope

4. Conclusions

Generation & recovery of N_{OT} in Off-state



6.5V 6.5V 6.0V T₀=27C 0 1000 2000 Time (s)

Relax

Stress

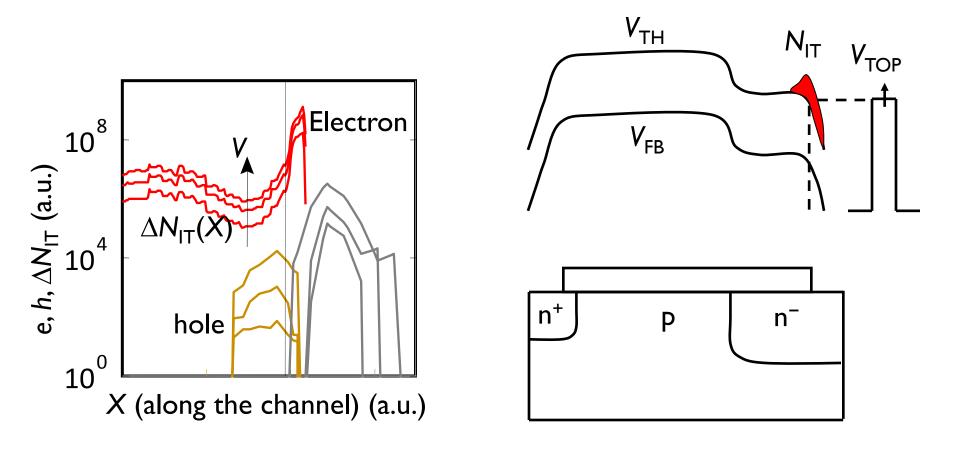
7.0V

Higher time exponents

No recovery

Most of the bonds broken are Si-O ...

Correlation of hot hole and $N_{\rm IT}$



Lateral profiling of $N_{\rm IT}$ correlates well with hot carrier profile by SMC

Recall: voltage dependent constant t_0

$$N_{\rm IT}^{\rm SiH} = \left(\frac{k_{\rm F}(V_{\rm G}, V_{\rm D})N_0}{k_{\rm R}}\right)^{\alpha} t^n \equiv \left(\frac{t}{t_0}\right)^n = f_1\left(\frac{t}{t_0}\right)$$

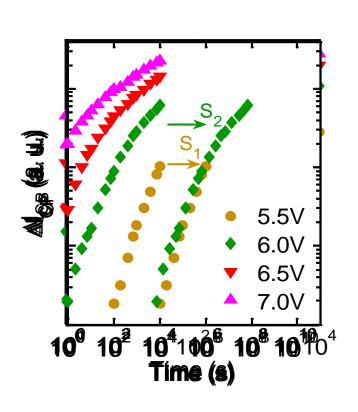
$$N_{
m IT}^{
m SiO} = \sum_{\mathcal{E}} g(\mathcal{E}) \left[1 + e^{-k_{
m F}(V_{
m G}, V_{
m D})t} \right] d\mathcal{E} \equiv f_2 \left(\frac{t}{t_0} \right)$$

$$t_0^{-1}(V_{\rm G}, V_{\rm D}) = I_{\rm G} = k \frac{I_{\rm D}}{W_{\rm eff}} \left[\frac{I_{\rm sub}}{I_{\rm D}} \right]^{\Phi_{\rm ii}/\Phi_{\rm i}}$$

How to determine t_0 ...

$$t^*/t_0(V_{\rm G}, V_{\rm D}) = f^{-1}(N_{\rm IT}^*) = {\rm const.}$$

 $t_0(V_{\rm G}, V_{\rm D}) \propto t^*(V_{\rm G}, V_{\rm D})$

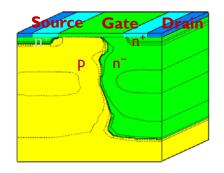


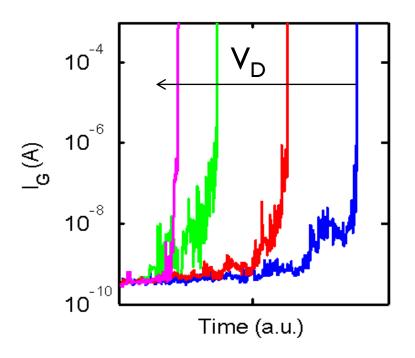
Outline

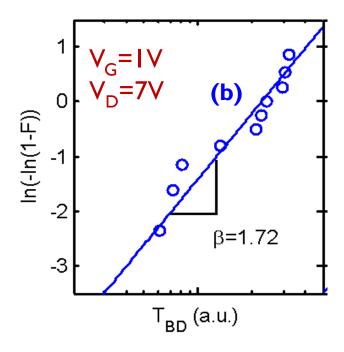
- I. Recall: ON vs. OFF State HCI Degradation
- 2. SiH vs. SiO bonds and theory of universal scaling
- 3. Dielectric Breakdown during HCI
- 4. Conclusions

Alam ECE-695

HCI leads to dielectric breakdown!

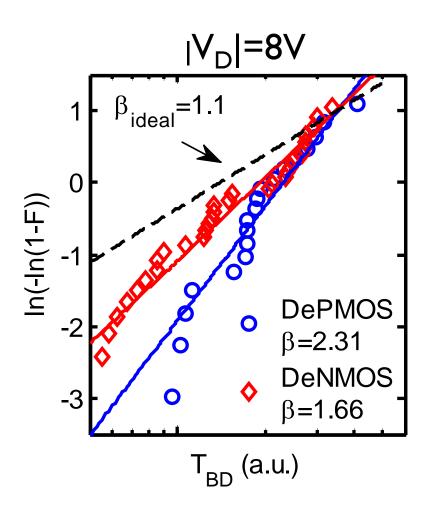






14

Weibull slopes for NMOS and PMOS



Classical theory suggests

$$\beta_{\text{ideal}} \equiv M \times \alpha \equiv \frac{x_{\text{o}}}{a_{\text{o}}} \alpha$$

$$\beta_{PMOS} > \beta_{NMOS} > \beta_{ideal}$$

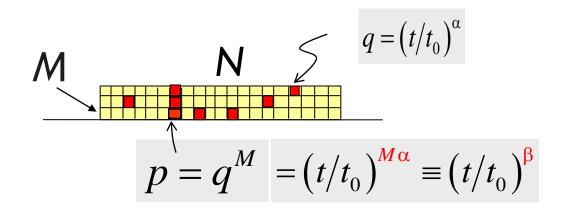
$$X_{o,PMOS}$$
 VS. $X_{o,NMOS}$

$$a_{0,PMOS}$$
 vs. $a_{0,NMOS}$

$$\alpha_{0,PMOS}$$
 vs. $\alpha_{0,NMOS}$

There is a problem here, a test for percolation theory!

Number Weibull vs. time Weibull



The number of boxes filled at failure vs.
Time to failure

$$P_0 = (1-p)^N = (1-Np/N)^N = \exp(-Np)$$

$$1 - F(p) = P_0 = \exp(-Np)$$

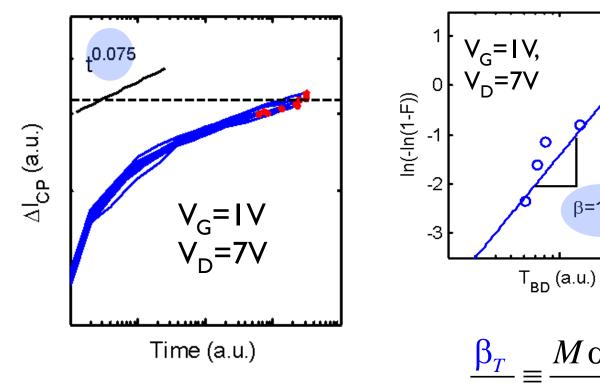
$$\frac{\beta_{\text{time}}}{\beta_{\text{Number}}} \equiv \frac{M\alpha}{M} = \alpha$$

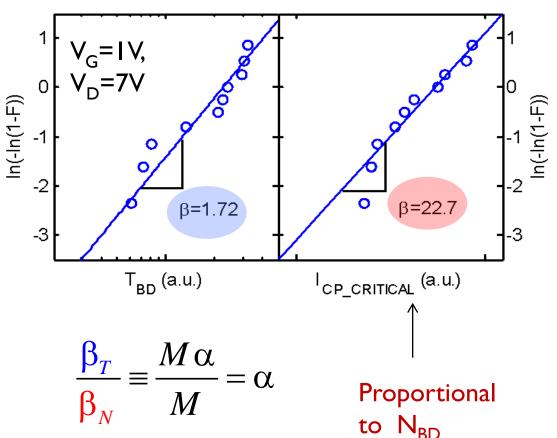
$$W_{\text{number}} \equiv \ln(-\ln(1-F)) = M \times \ln(q) + \ln(N)$$

$$W_{\text{Time}} \equiv \ln(-\ln(1-F)) = M\alpha \ln(t) - M\alpha \ln(t_0) + \ln(N)$$

Checking time exponent α (DeNMOS)

Use CP or SILC for Number Weibull, TDB for time-Weibull

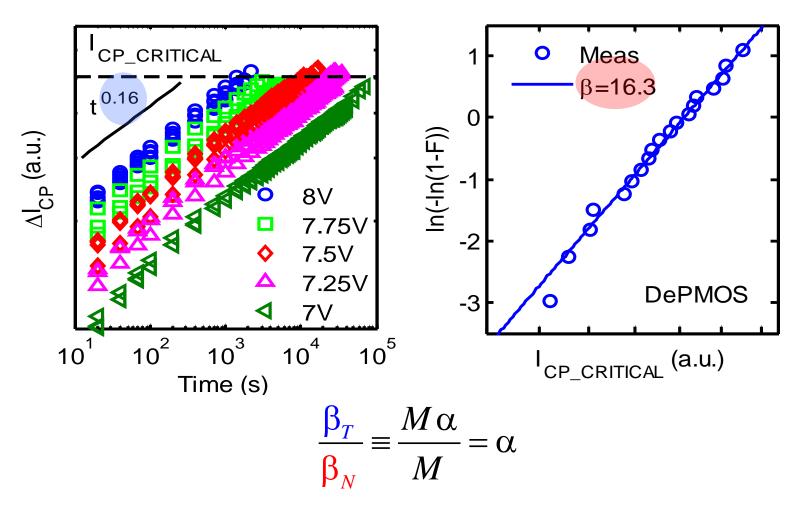




Verified, nothing wrong with exponent!

Alam ECE-695

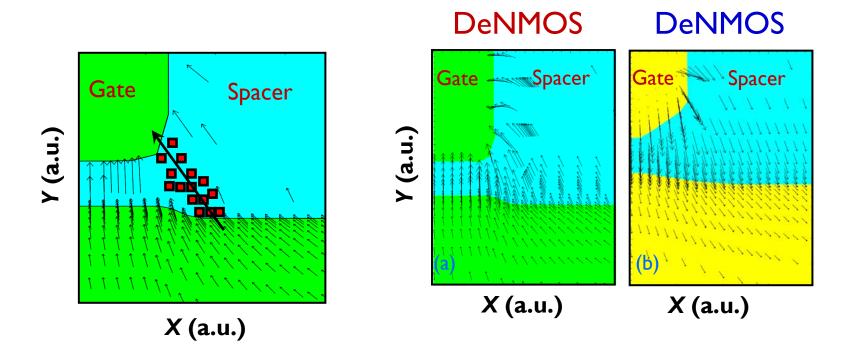
Checking power exponent α (DePMOS)



Again, nothing wrong with exponent!

Alam ECE-695

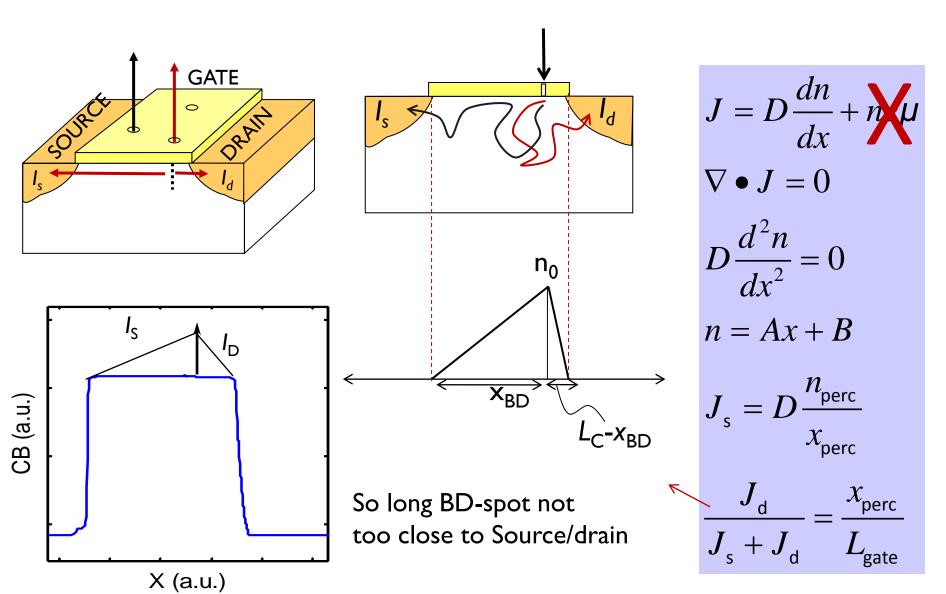
Hypothesis: Perhaps x_0 is not the same!



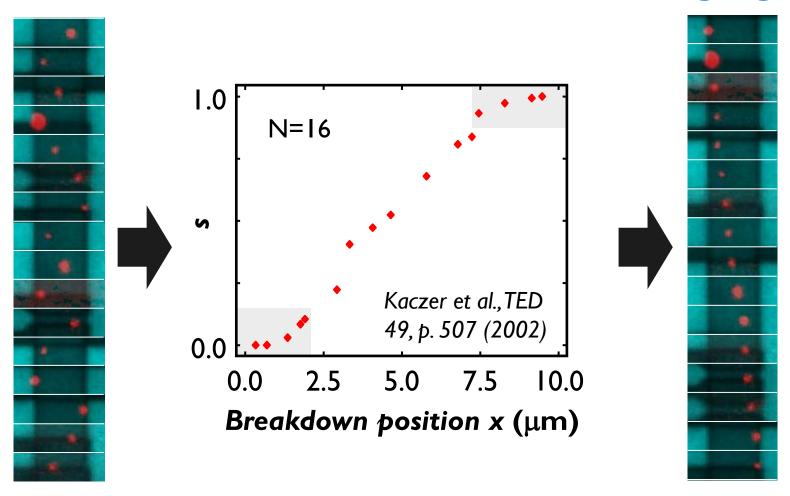
Perhaps the breakdown paths are larger than oxide thickness

Perhaps the path-lengths of NMOS and PMOS are different

Recall: Current ratio technique

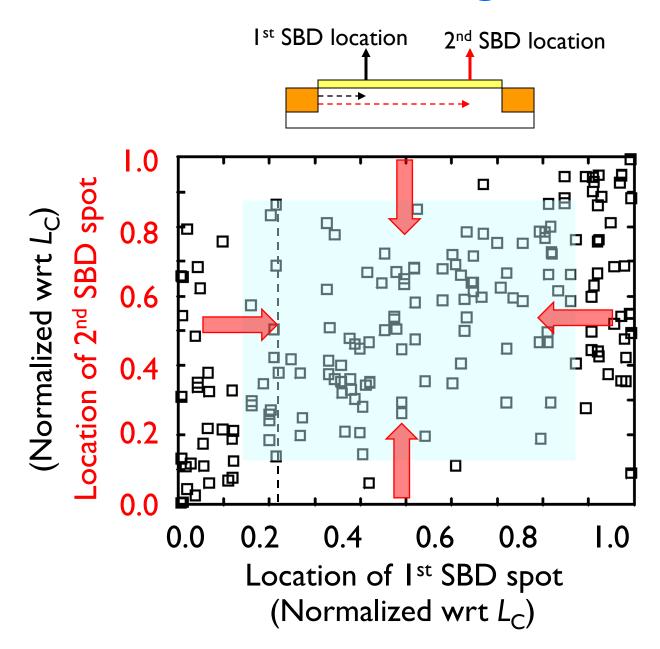


Locations close to S/D are challenging

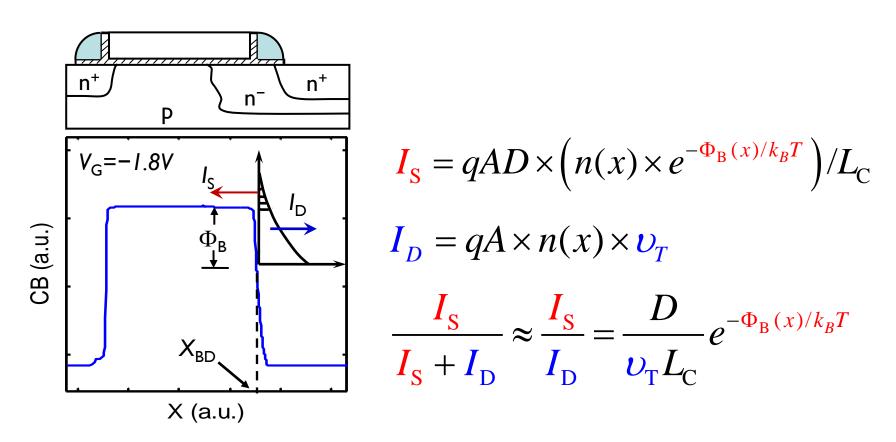


Emission microscopy on $L=10 \mu m$ nFETs confirms the BD position determination method.

Rational for S/D region exclusion

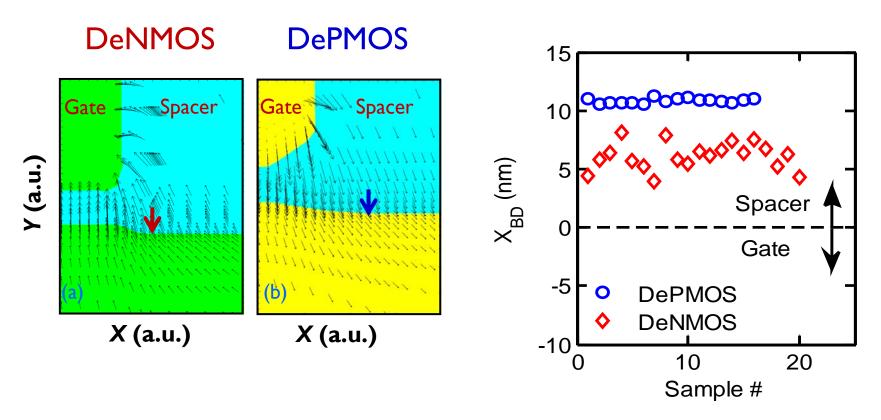


Determination of breakdown spot for a nonuniform potential profile



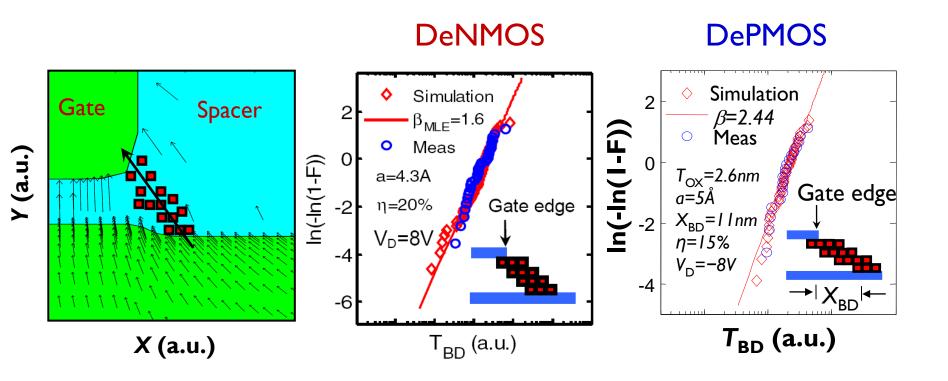
Experiment (LHS) and simulation (RHS) locates BD spot

Position determination in non-uniform field



Breakdown occurred in DePMOS slightly further down in the channel compared to DeNMOS

Correlated percolation and TDDB



$$T_{\text{ox,PMOS}} > T_{\text{ox,NMOS}}!$$
 $a_{0,PMOS} = a_{0,NMOS}$ (same defect-size)

Same parameter set explains both set of data

Alam ECE-695 26

Conclusions

- Off state HCI degradation appears to be a general phenomena for wide variety of high voltage transistors, including LDMOS, DeNMOS, DePMOS, etc.
- ☐ The degradation process follows the same universal relationship as has been discussed for classical ON-state degradation.
- The remarkable fact is the off-state HCI often leads to TDDB which gives rise to many puzzling features.
- Appropriate use of BD position and non-uniform percolation resolves the puzzles about Weibull slopes and power-exponents and in the process establishes percolation theory on solid footing.

Alam ECE-695 27

Self-Test Questions

- In PMOS transistors, which carriers is responsible for off-state HCI?
- 2. What is the distinction between number-Weibull and time-Weibull?
- 3. Which measurement is used to determine Number-Weibull? Name another technique that could do the same.
- 4. What is 'area-scaling'? Will area-scaling hold for off-state BD?
- 5. What conditions in general must be satisfied for area scaling?
- 6. How did the gate electric field profile influence percolation simulation?
- 7. For universal curve, is the value of power exponent a fixed number? If not, what exponent should we choose and why?

Alam ECE-695

28